

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Name MINI50 RAHDR SMT 8CKT GRY POL B T&R

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MINI50 RAHDR SMT 8CKT GRY POL B T&R	Assembly		100	2.174324
MINI50 HSNG RAHDR SMT 8CKT GRY POL B	Component		78.1852	1.7
PS-ST GF30	Material		78.1852	1.7
PS-ST	Substance		45.885	0.997688
GF-Fibre	Substance		23.3578	0.507875
Pigment portion, not to declare	Substance	system	0.9578	0.020825
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	5.3215	0.115707
Further Additives, not to declare	Substance	system	2.6631	0.057905
MINI50 TERM SMT SOLDER NAIL LT MATTE SN	Component		6.1168	0.133
Cartridge Brass 70% Unplated	Material		5.7489	0.125
Copper	Substance	7440-50-8	4.0242	0.0875
Zinc (metal)	Substance	7440-66-6	1.7247	0.0375
Nickel Plating	Material		0.1288	0.0028

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Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)	
Nickel	Substance	7440-02-0	7440-02-0 0.1288		
Further Additives, not to declare	Substance	system	1E-05	3E-07	
Tin Plating	Material	0.2392		0.0052	
Tin	Substance	7440-31-5	7440-31-5 0.2392		
MINI50 TERM SMT SOLDER NAIL RT MATTE SN	Component	5.7489		0.125	
Cartridge Brass 70% Unplated	Material		5.381		
Copper	Substance	7440-50-8	7440-50-8 3.7667		
Zinc (metal)	Substance	7440-66-6	7440-66-6 1.6143		
Nickel Plating	Material		0.1288		
Nickel	Substance	7440-02-0	7440-02-0 0.1288		
Further Additives, not to declare	Substance	system 1E-05		3E-07	
Tin Plating	Material	0.2392		0.0052	
Tin	Substance	7440-31-5	0.2392	0.0052	
MINI50 TERM BLD 0.50X15.57 AU	Component	9.949		0.216324	
Cartridge Brass 70% Unplated	Material		8.8303		
Copper	Substance	7440-50-8	7440-50-8 6.1812		
Zinc (metal)	Substance	7440-66-6	7440-66-6 2.6491		
Nickel Plating	Material		0.5887	0.0128	
Nickel	Substance	7440-02-0	0.5886	0.012799	
Further Additives, not to declare	Substance	system	6E-05	0.000001	
Tin Plating	Material		0.3492	0.007594	
Tin	Substance	7440-31-5	0.3492	0.007594	
Gold Plating	Material	0.1808		0.00393	
Cobalt	Substance	7440-48-4	0.0005	0.00001	
Nickel	Substance	7440-02-0	0.0005	0.00001	
Gold	Substance	7440-57-5	0.1799	0.003911	

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Not reviewed

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)4578-DC (25 June 2020)

Contained Substances Exceeding Threshold

None

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

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China ROHS Declaration Information

Part Number 0349126081

Part Name MINI50 RAHDR SMT 8CKT GRY POL

B T&R





Hazardous Substances

Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MINI50 RAHDR SMT 8CKT GRY POL B T&R	0	0	0	0	0	0
MINI50 HSNG RAHDR SMT 8CKT GRY POL B	0	0	0	0	0	0
MINI50 TERM SMT SOLDER NAIL LT MATTE SN	0	0	0	0	0	0
MINI50 TERM SMT SOLDER NAIL RT MATTE SN	0	0	0	0	0	0
MINI50 TERM BLD 0.50X15.57 AU	0	0	0	0	0	0

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Feb 11, 2021